

Title (en)
THERMOSETTING RESIN COMPOSITION, EPOXY RESIN MOLDING MATERIAL, AND POLYVALENT CARBOXYLIC ACID CONDENSATE

Title (de)
WÄRMEHÄRTENDE HARZZUSAMMENSETZUNG, EPOXIDHARZ-FORMMATERIAL UND POLYVALENTES CARBOXYLSÄURE-KONDENSAT

Title (fr)
COMPOSITION DE RÉSINE THERMODURCISSABLE, MATÉRIAU DE MOULAGE EN RÉSINE ÉPOXY ET CONDENSAT D'ACIDE CARBOXYLIQUE POLYVALENT

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Application
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Abstract (en)
The epoxy resin molding material of the invention comprises (A) an epoxy resin and (B) a curing agent, wherein the (B) curing agent contains a polyvalent carboxylic acid condensate. The thermosetting resin composition of the invention comprises (A) an epoxy resin and (B) a curing agent, wherein the viscosity of the (B) curing agent is 1.0-1000 mPa·s at 150 °C, as measured with an ICI cone-plate Brookfield viscometer.

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